PIC16F8XX

EEPROM Memory Programming Specification

This document includes the programming specifications for the following devices:

- PIC16F870
- PIC16F871
- PIC16F872
- PIC16F873
- PIC16F874
- PIC16F876
- PIC16F877

1.0 PROGRAMMING THE PIC16F8XX

The PIC16F8XX is programmed using a serial method. The serial mode will allow the PIC16F8XX to be programmed while in the users system. This allows for increased design flexibility. This programming specification applies to PIC16F8XX devices in all packages.

PIC16F8XX devices may be programmed using a single +5 volt supply (low voltage programming mode).

1.1 Hardware Requirements

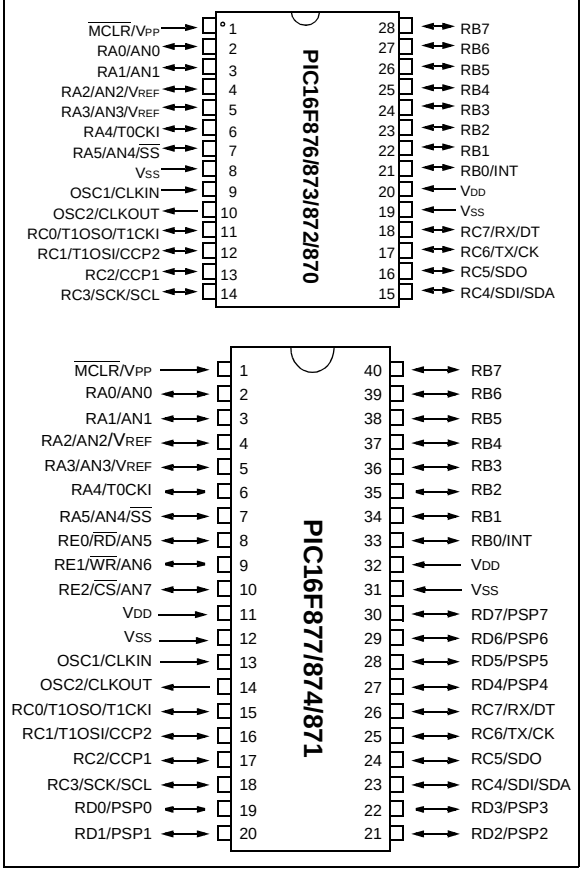
The PIC16F8XX requires one programmable power supply for VDD (4.5V to 5.5V) and a VPP of 12V to 14V or VPP of (4.5V to 5.5V) when using low voltage In-Circuit Serial Programming™ (ICSP™). Both supplies should have a minimum resolution of 0.25V.

1.2 Programming Mode

The programming mode for the PIC16F8XX allows programming of user program memory, data memory, special locations used for ID, and the configuration word.

Pin Diagram

PDIP, SOIC



PIN DESCRIPTIONS (DURING PROGRAMMING): PIC16F8XX

Pin Name	During Programming		
	Function	Pin Type	Pin Description
RB3	PGM	I	Low voltage ICSP programming input if configuration bit equals 1
RB6	CLOCK	I	Clock input
RB7	DATA	I/O	Data input/output
MCLR	VTEST MODE	P*	Program Mode Select
VDD	VDD	P	Power Supply
VSS	VSS	P	Ground

Legend: I = Input, O = Output, P = Power

*In the PIC16F8XX, the programming high voltage is internally generated. To activate the programming mode, high voltage needs to be applied to MCLR input. Since the MCLR is used for a level source, this means that MCLR does not draw any significant current.

In-circuit Serial Programming (ICSP) is a trademark of Microchip Technology Inc.

2.0 PROGRAM MODE ENTRY

2.1 User Program Memory Map

The user memory space extends from 0x0000 to 0x1FFF (8K). In programming mode the program memory space extends from 0x0000 to 0x3FFF, with the first half (0x0000-0x1FFF) being user program memory and the second half (0x2000-0x3FFF) being configuration memory. The PC will increment from 0x0000 to 0x1FFF and wrap to 0x000, 0x2000 to 0x3FFF and wrap around to 0x2000 (not to 0x0000). Once in configuration memory, the highest bit of the PC stays a '1', thus always pointing to the configuration memory. The only way to point to user program memory is to reset the part and reenter program/verify mode as described in Section 2.3.

In the configuration memory space, 0x2000-0x200F are physically implemented. However, only locations 0x2000 through 0x2007 are available. Other locations are reserved. Locations beyond 0x200F will physically access user memory. (See Figure 2-1).

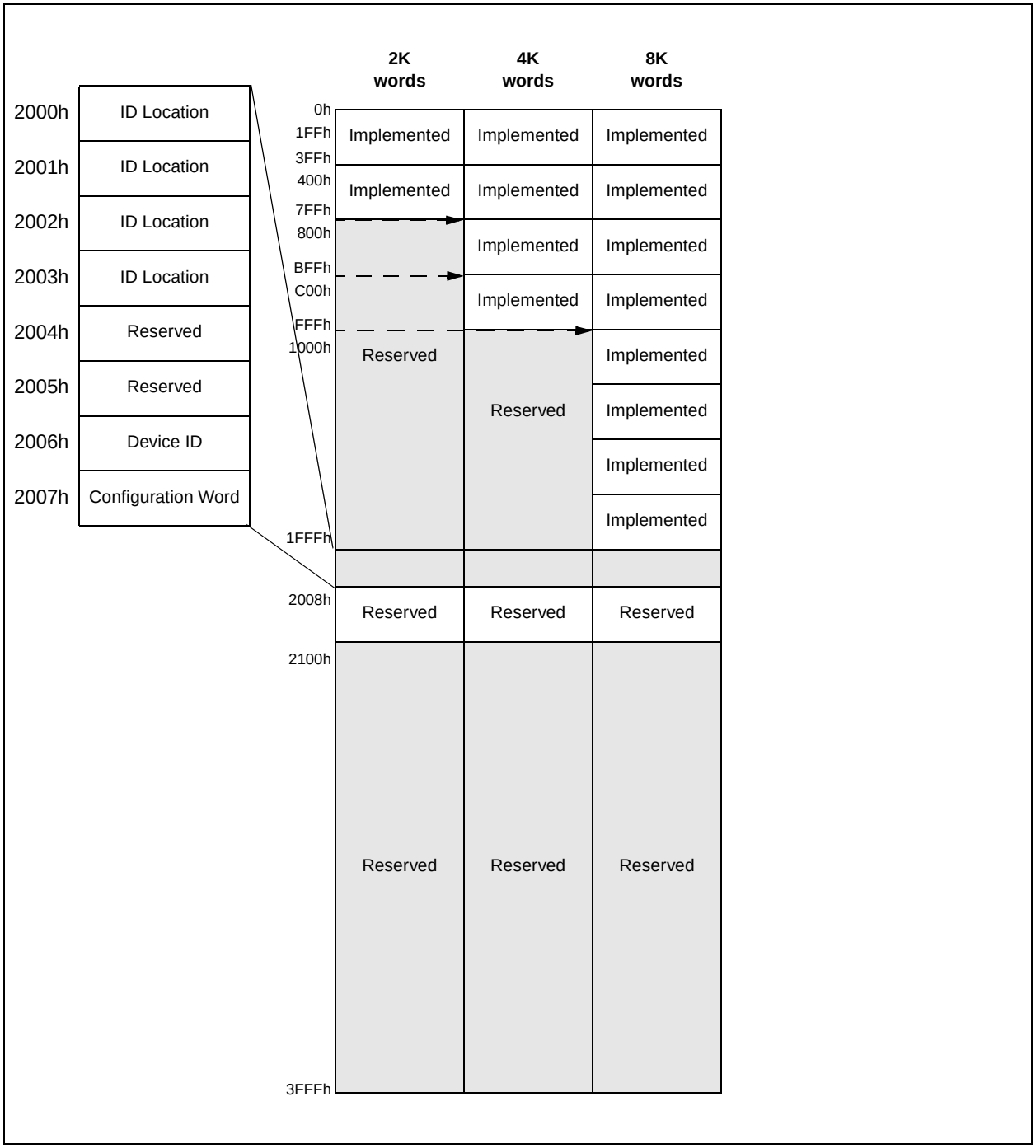
2.2 ID Locations

A user may store identification information (ID) in four ID locations. The ID locations are mapped in [0x2000 : 0x2003]. It is recommended that the user use only the four least significant bits of each ID location. In some devices, the ID locations read-out in an unscrambled fashion after code protection is enabled. For these devices, it is recommended that ID location is written as "11 1111 1000 bbbb" where 'bbbb' is ID information.

In other devices, the ID locations read out normally, even after code protection. To understand how the devices behave, refer to Table 4-1.

To understand the scrambling mechanism after code protection, refer to Section 4.0.

FIGURE 2-1: PROGRAM MEMORY MAPPING



2.3 Program/Verify Mode

The program/verify mode is entered by holding pins RB6 and RB7 low while raising MCLR pin from VIL to VIHH (high voltage). In this mode, the state of the RB3 pin does not effect programming. Low-voltage ICSP programming mode is entered by applying VDD to MCLR and raising RB3 from VIL to VDD. Once in this mode the user program memory and the configuration memory can be accessed and programmed in serial fashion. The mode of operation is serial, and the memory that is accessed is the user program memory. RB6 and RB7 are Schmitt Trigger Inputs in this mode.

Note:	The OSC must not have 72 osc clocks while the device MCLR is between VIL and VIHH.

The sequence that enters the device into the programming/verify mode places all other logic into the reset state (the MCLR pin was initially at VIL). This means that all I/O are in the reset state (High impedance inputs).

The normal sequence for programming is to use the load data command to set a value to be written at the selected address. Issue the begin programming command followed by read data command to verify, and then increment the address.

A device reset will clear the PC and set the address to 0. The “increment address” command will increment the PC. The “load configuration” command will se the PC to 0x2000. The available commands are shown in Table 2-1.

2.3.1 LOW-VOLTAGE ICSP PROGRAMMING MODE

When LVP bit is set to ‘1’, the low-voltage ICSP programming entry is enabled. Since the LVP configuration bit allows low voltage ICSP programming entry in its erased state, an erased device will have the LVP bit enabled at the factory. While LVP is ‘1’, RB3 is dedicated to low voltage ICSP programming. Bring MCLR to VDD and then RB3 to VDD to enter programming mode. All other specifications for high-voltage ICSP™ apply.

To disable low voltage ICSP mode, the LVP bit must be programmed to ‘0’. This must be done while entered with high voltage entry mode (LVP bit= 1). RB3 is now a general purpose I/O pin.

2.3.2 SERIAL PROGRAM/VERIFY OPERATION

The RB6 pin is used as a clock input pin, and the RB7 pin is used for entering command bits and data input/output during serial operation. To input a command, the clock pin (RB6) is cycled six times. Each command bit is latched on the falling edge of the clock with the least significant bit (LSB) of the command being input first. The data on pin RB7 is required to have a minimum setup and hold time (see AC/DC specifications) with respect to the falling edge of the clock. Commands that have data associated with them (read and load) are specified to have a minimum delay of 1 µs between the command and the data. After this delay, the clock pin is cycled 16 times with the first cycle being a start bit and the last cycle being a stop bit. Data is also input and output LSB first.

Therefore, during a read operation the LSB will be transmitted onto pin RB7 on the rising edge of the second cycle, and during a load operation the LSB will be latched on the falling edge of the second cycle. A minimum 1µs delay is also specified between consecutive commands.

All commands are transmitted LSB first. Data words are also transmitted LSB first. The data is transmitted on the rising edge and latched on the falling edge of the clock. To allow for decoding of commands and reversal of data pin configuration, a time separation of at least 1 µs is required between a command and a data word (or another command).

The commands that are available are:

2.3.2.1 LOAD CONFIGURATION

After receiving this command, the program counter (PC) will be set to 0x2000. By then applying 16 cycles to the clock pin, the chip will load 14-bits in a “data word,” as described above, to be programmed into the configuration memory. A description of the memory mapping schemes of the program memory for normal operation and configuration mode operation is shown in Figure 2-1. After the configuration memory is entered, the only way to get back to the user program memory is to exit the program/verify test mode by taking MCLR low (VIL).

2.3.2.2 LOAD DATA FOR PROGRAM MEMORY

After receiving this command, the chip will load in a 14-bit “data word” when 16 cycles are applied, as described previously. A timing diagram for the load data command is shown in Figure 5-1.

TABLE 2-1: COMMAND MAPPING FOR PIC16F84A/PIC16F877

Command	Mapping (MSB … LSB)						Data
Load Configuration	X	X	0	0	0	0	0, data (14), 0
Load Data for Program Memory	X	X	0	0	1	0	0, data (14), 0
Read Data from Program Memory	X	X	0	1	0	0	0, data (14), 0
Increment Address	X	X	0	1	1	0	
Begin Erase Programming Cycle	0	0	1	0	0	0	
Begin Programming Only Cycle	0	1	1	0	0	0	
Load Data for Data Memory	X	X	0	0	1	1	0, data (14), 0
Read Data from Data Memory	X	X	0	1	0	1	0, data (14), 0
Bulk Erase Program Memory	X	X	1	0	0	1	
Bulk Erase Data Memory	X	X	1	0	1	1	

FIGURE 2-2: PROGRAM FLOW CHART - PIC16F8XX PROGRAM MEMORY

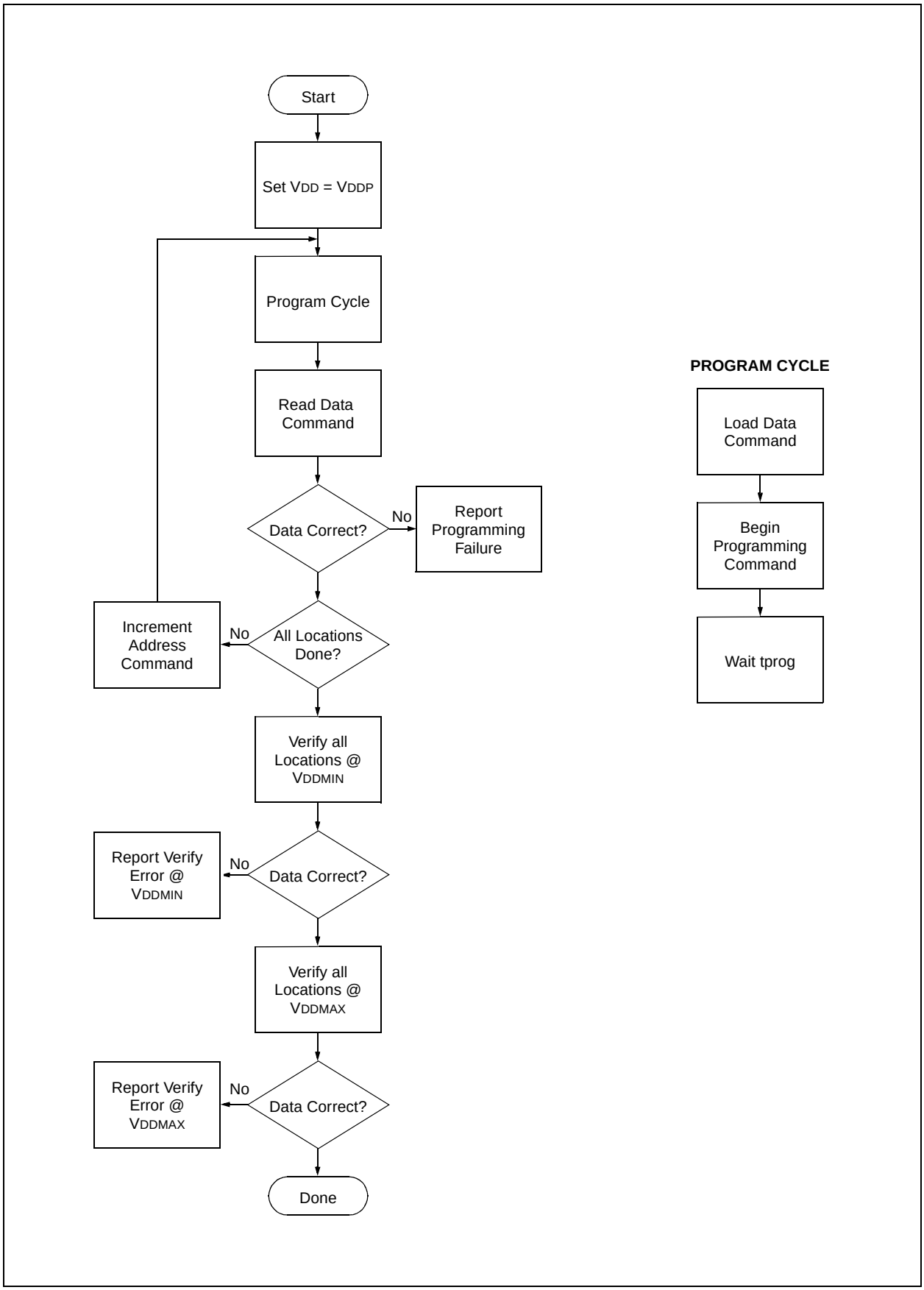
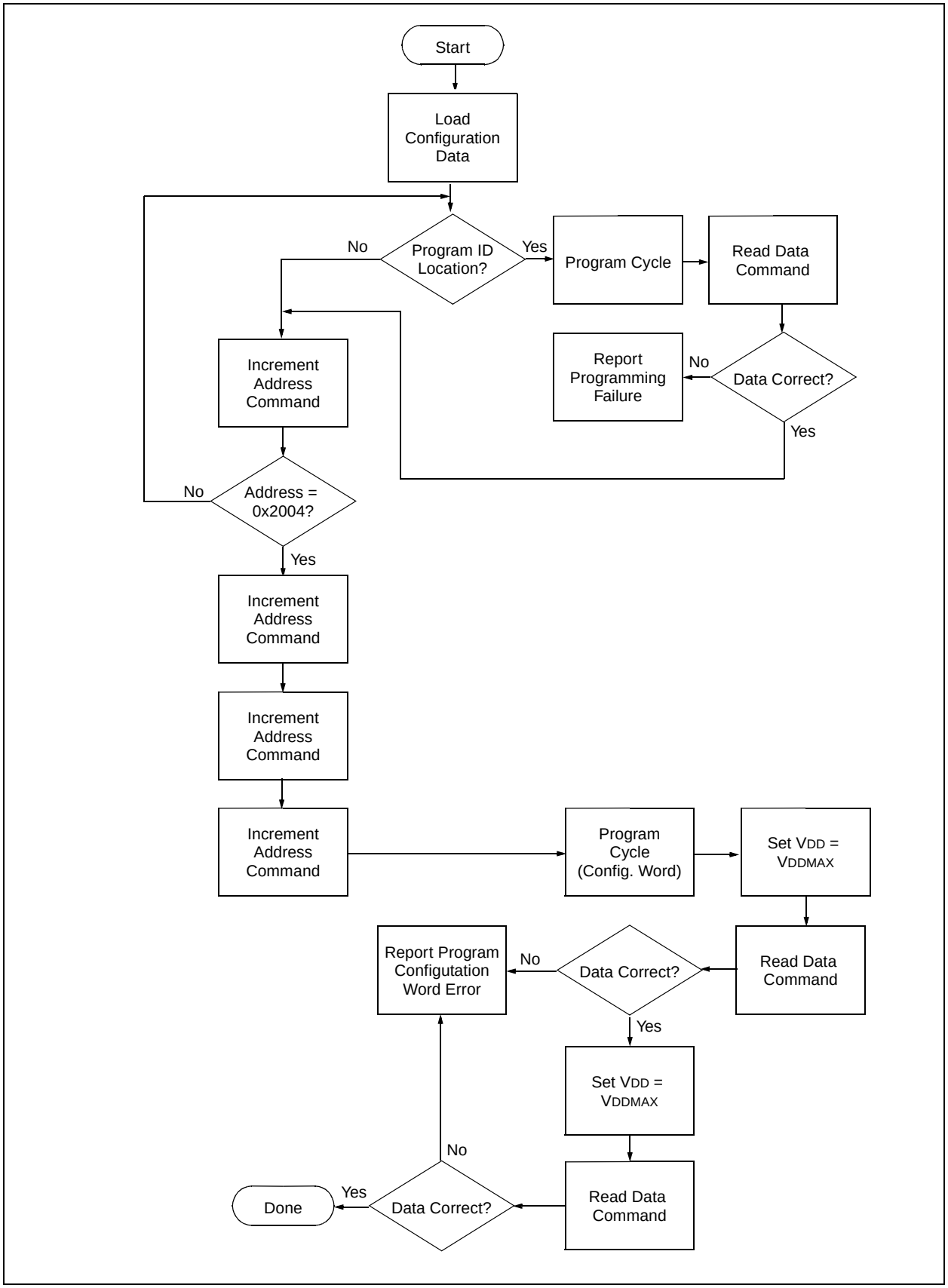


FIGURE 2-3: PROGRAM FLOW CHART - PIC16F8XX CONFIGURATION MEMORY



2.3.2.3 LOAD DATA FOR DATA MEMORY

After receiving this command, the chip will load in a 14-bit "data word" when 16 cycles are applied. However, the data memory is only 8-bits wide, and thus only the first 8-bits of data after the start bit will be programmed into the data memory. It is still necessary to cycle the clock the full 16 cycles in order to allow the internal circuitry to reset properly. The data memory contains 64 words. Only the lower 8-bits of the PC are decoded by the data memory, and therefore if the PC is greater than 0x3F, it will wrap around and address a location within the physically implemented memory. If the device is code protected, the data is read as all zeros.

2.3.2.4 READ DATA FROM PROGRAM MEMORY

After receiving this command, the chip will transmit data bits out of the program memory (user or configuration) currently accessed starting with the second rising edge of the clock input. The RB7 pin will go into output mode on the second rising clock edge, and it will revert back to input mode (hi-impedance) after the 16th rising edge. A timing diagram of this command is shown in Figure 5-2.

2.3.2.5 READ DATA FROM DATA MEMORY

After receiving this command, the chip will transmit data bits out of the data memory starting with the second rising edge of the clock input. The RB7 pin will go into output mode on the second rising edge, and it will revert back to input mode (hi-impedance) after the 16th rising edge. As previously stated, the data memory is 8-bits wide, and therefore, only the first 8-bits that are output are actual data.

2.3.2.6 INCREMENT ADDRESS

The PC is incremented when this command is received. A timing diagram of this command is shown in Figure 5-3.

2.3.2.7 BEGIN ERASE/PROGRAM CYCLE

A load command must be given before every begin programming command. Programming of the appropriate memory (test program memory, user program memory or data memory) will begin after this command is received and decoded. An internal timing mechanism executes an erase before write. The user must allow for both erase and programming cycle times for programming to complete. No "end programming" command is required.

2.3.2.8 BEGIN PROGRAMMING

A load command must be given before every begin programming command. Programming of the appropriate memory (test program memory, user program memory or data memory) will begin after this command is received and decoded. An internal timing mechanism executes a write. The user must allow for program cycle time for programming to complete. No "end programming" command is required.

This command is similar to the ERASE/PROGRAM CYCLE command, except that a word erase is not done. It is recommended that a bulk erase be performed before starting a series of programming only cycles.

2.3.2.9 BULK ERASE PROGRAM MEMORY

After this command is performed, the next program command will erase the entire program memory.

To perform a bulk erase of the program memory, the following sequence must be performed.

1. Do a "Load Data All 1's" command.
2. Do a "Bulk Erase Program Memory" command.
3. Do a "Begin Programming" command.
4. Wait 10 ms to complete bulk erase.

If the address is pointing to the test program memory (0x2000 - 0x200F), then both the user memory and the test memory will be erased. The configuration word will not be erased, even if the address is pointing to location 0x2007.

Note:	If the device is code-protected, the BULK ERASE command will not work.

2.3.2.10 BULK ERASE DATA MEMORY

To perform a bulk erase of the data memory, the following sequence must be performed.

1. Do a "Load Data All 1's" command.
2. Do a "Bulk Erase Data Memory" command.
3. Do a "Begin Programming" command.
4. Wait 10 ms to complete bulk erase.

Note:	All BULK ERASE operations must take place at 4.5 to 5.5 V_{DD} range.

2.4 Programming Algorithm Requires Variable VDD

The PIC16F8XX uses an intelligent algorithm. The algorithm calls for program verification at VDDmin. as well as VDDmax. Verification at VDDmin. guarantees good “erase margin”. Verification at VDDmax guarantees good “program margin”.

The actual programming must be done with VDD in the VDDP range (See Table 5-1).

VDDP = VCC range required during programming.

VDDmin. = minimum operating VDD spec for the part.

VDDmax. = maximum operating VDD spec for the part.

Programmers must verify the PIC16F8XX at its specified VDD max. and VDDmin levels. Since Microchip may introduce future versions of the PIC16F8XX with a broader VDD range, it is best that these levels are user selectable (defaults are ok).

Note:	Any programmer not meeting these requirements may only be classified as “prototype” or “development” programmer but not a “production” quality programmer.

3.0 CONFIGURATION WORD

The PIC16F8XX has several configuration bits. These bits can be set (reads '0') or left unchanged (reads '1') to select various device configurations.

3.1 Device ID Word

The device ID word for the PIC16F8XX is located at 2006h.

TABLE 3-1: DEVICE ID VALUE

Device	Device ID Value	
	Dev	Rev
PIC16F870	00 1101 000	x xxxx
PIC16F871	00 1101 001	x xxxx
PIC16F872	00 1000 111	x xxxx
PIC16F873	00 1001 011	x xxxx
PIC16F874	00 1001 001	x xxxx
PIC16F876	00 1001 111	x xxxx
PIC16F877	00 1001 101	x xxxx

FIGURE 3-1: CONFIGURATION WORD FOR PIC16F873/874/876/877

CP1	CP0	RESV	-	WRT	CPD	LVP	BODEN	CP1	CP0	$\overline{\text{PWRTE}}$	WDTE	F0SC1	F0SC0
bit13													bit0

Register: CONFIG
Address 2007h

bit 13-12:

bit 11: **Reserved:** Set to '1' for normal operation

bit 5-4: **CP1:CP0**: Flash Program Memory Code Protection bits (2)

4K Devices:
- 11 = Code protection off
- 10 = not supported
- 01 = not supported
- 00 = 0000h to 0FFFh code protected

8K Devices:
- 11 = Code protection off
- 10 = 1F00h to 1FFFh code protected
- 01 = 1000h to 1FFFh code protected
- 00 = 0000h to 1FFFh code protected

bit 11: **Reserved**: Set to '1' for normal operation

bit 10: **Unimplemented**: Read as '1'

bit 9: **WRT**: Flash Program Memory Write Enable
- 1 = Unprotected program memory may be written to by EECON control
- 0 = Unprotected program memory may not be written to by EECON control

bit 8: **CPD**: Data EE Memory Code Protection
- 1 = Code protection off
- 0 = Data EE memory code protected

bit 7: **LVP**: Low voltage programming Enable bit
- 1 = RB3/PGM pin has PGM function, low voltage programming enabled
- 0 = RB3 is digital I/O, HV on $\overline{\text{MCLR}}$ must be used for programming

bit 6: **BODEN**: Brown-out Reset Enable bit (1)
- 1 = BOR enabled
- 0 = BOR disabled

bit 3: **$\overline{\text{PWRTE}}$**: Power-up Timer Enable bit (1)
- 1 = PWRT disabled
- 0 = PWRT enabled

bit 2: **WDTE**: Watchdog Timer Enable bit
- 1 = WDT enabled
- 0 = WDT disabled

bit 1-0: **FOSC1:FOSC0**: Oscillator Selection bits
- 11 = RC oscillator
- 10 = HS oscillator
- 01 = XT oscillator
- 00 = LP oscillator

Note 1: Enabling Brown-out Reset automatically enables Power-up Timer (PWRT) regardless of the value of bit $\overline{\text{PWRTE}}$. Ensure the Power-up Timer is enabled anytime Brown-out Reset is enabled.

2: All of the CP1:CP0 pairs have to be given the same value to enable the code protection scheme listed.

FIGURE 3-2: CONFIGURATION WORD FOR PIC16F870/871/872

CP1	CP0	RESV	-	WRT	CPD	LVP	BODEN	CP1	CP0	$\overline{\text{PWRTE}}$	WDTE	F0SC1	F0SC0
bit13													bit0

Register: CONFIG
Address 2007h

bit 13-12:

bit 5-4: **CP1:CP0**: Flash Program Memory Code Protection bits **(2)**
- 11 = Code protection off
- 10 = not supported
- 01 = not supported
- 00 = 0000h to 07FFh code protected

bit 11: **Reserved**: Set to '1' for normal operation

bit 10: **Unimplemented**: Read as '1'

bit 9: **WRT**: Flash Program Memory Write Enable
- 1 = Unprotected program memory may be written to by EECON control
- 0 = Unprotected program memory may not be written to by EECON control

bit 8: **CPD**: Data EE Memory Code Protection
- 1 = Code protection off
- 0 = Data EE memory code protected

bit 7: **LVP**: Low voltage programming Enable bit
- 1 = RB3/PGM pin has PGM function, low voltage programming enabled
- 0 = RB3 is digital I/O, HV on $\overline{\text{MCLR}}$ must be used for programming

bit 6: **BODEN**: Brown-out Reset Enable bit **(1)**
- 1 = BOR enabled
- 0 = BOR disabled

bit 3: **$\overline{\text{PWRTE}}$**: Power-up Timer Enable bit **(1)**
- 1 = PWRT disabled
- 0 = PWRT enabled

bit 2: **WDTE**: Watchdog Timer Enable bit
- 1 = WDT enabled
- 0 = WDT disabled

bit 1-0: **FOSC1:FOSC0**: Oscillator Selection bits
- 11 = RC oscillator
- 10 = HS oscillator
- 01 = XT oscillator
- 00 = LP oscillator

Note 1: Enabling Brown-out Reset automatically enables Power-up Timer (PWRT) regardless of the value of bit $\overline{\text{PWRTE}}$. Ensure the Power-up Timer is enabled anytime Brown-out Reset is enabled.

2: All of the CP1:CP0 pairs have to be given the same value to enable the code protection scheme listed.

4.0 CODE PROTECTION

For PIC16F8XX devices, once code protection is enabled, all program memory locations read all 0's. The ID locations and the configuration word read out in an unscrambled fashion. Further programming is disabled for the entire program memory as well as data memory. It is possible to program the ID locations and the configuration word.

4.1 Disabling Code-Protection

It is recommended that the following procedure be performed before any other programming is attempted. It is also possible to turn code protection off (code protect bit = 1) using this procedure; however, ***all data within the program memory and the data memory will be erased when this procedure is executed, and thus, the security of the data or code is not compromised.***

Procedure to disable code protect:

a) Execute load configuration (with a '1' in bit 13-4, code protect).
b) Increment to configuration word location (0x2007)
c) Execute command (000001)
d) Execute command (000111)
e) Execute 'Begin Programming' (001000)
f) Wait 12 ms
g) Execute command (000001)
h) Execute command (000111)

4.2 Embedding Configuration Word and ID Information in the Hex File

To allow portability of code, the programmer is required to read the configuration word and ID locations from the hex file when loading the hex file. If configuration word information was not present in the hex file then a simple warning message may be issued. Similarly, while saving a hex file, configuration word and ID information must be included. An option to not include this information may be provided.

Specifically for the PIC16F8XX, the EEPROM data memory should also be embedded in the hex file (see Section 5.1).

Microchip Technology Inc. feels strongly that this feature is important for the benefit of the end customer.

4.3 CHECKSUM COMPUTATION

4.3.1 CHECKSUM

Checksum is calculated by reading the contents of the PIC16F8XX memory locations and adding up the opcodes up to the maximum user addressable location, e.g., 0x1FF for the PIC16F8XX. Any carry bits exceeding 16-bits are neglected. Finally, the configuration word (appropriately masked) is added to the checksum. Checksum computation for each member of the PIC16F8XX devices is shown in Table 4-1.

The checksum is calculated by summing the following:

- The contents of all program memory locations
- The configuration word, appropriately masked
- Masked ID locations (when applicable)

The least significant 16 bits of this sum is the checksum.

The following table describes how to calculate the checksum for each device. Note that the checksum calculation differs depending on the code protect setting. Since the program memory locations read out differently depending on the code protect setting, the table describes how to manipulate the actual program memory values to simulate the values that would be read from a protected device. When calculating a checksum by reading a device, the entire program memory can simply be read and summed. The configuration word and ID locations can always be read.

Note that some older devices have an additional value added in the checksum. This is to maintain compatibility with older device programmer checksums.

TABLE 4-1: CHECKSUM COMPUTATION

Device	Code Protect	Checksum*	Blank"Value	0x25E6 at 0 and max address
PIC16F870	OFF	SUM[0x0000:0x07FFF] + CFGW & 0x3BFF	0x33FF	0xFFCD
	ALL	CFGW & 0x3BFF + SUM_ID	0x3FCE	0x0B9C
PIC16F871	OFF	SUM[0x0000:0x07FFF] + CFGW & 0x3BFF	0x33FF	0xFFCD
	ALL	CFGW & 0x3BFF + SUM_ID	0x3FCE	0x0B9C
PIC16F872	OFF	SUM[0x0000:0x07FFF] + CFGW & 0x3BFF	0x33FF	0xFFCD
	ALL	CFGW & 0x3BFF + SUM_ID	0x3FCE	0x0B9C
PIC16F873	OFF	SUM[0x0000:0x0FFF] + CFGW & 0x3BFF	0x2BFF	0xF7CD
	0x0F00 : 0xFFF	SUM[0x0000:0x0EFF] + CFGW & 0x3BFF +SUM_ID	0x48EE	0xFAA3
	0x0800 : 0xFFF	SUM[0x0000:0x07FF] + CFGW & 0x3BFF + SUM_ID	0x3FDE	0xF193
	ALL	CFGW & 0x3BFF + SUM_ID	0x37CE	0x039C
PIC16F874	OFF	SUM[0x0000:0x0FFF] + CFGW & 0x3BFF	0x2BFF	0xF7CD
	0x0F00 : 0xFFF	SUM[0x0000:0x0EFF] + CFGW & 0x3BFF +SUM_ID	0x48EE	0xFAA3
	0x0800 : 0xFFF	SUM[0x0000:0x07FF] + CFGW & 0x3BFF + SUM_ID	0x3FDE	0xF193
	ALL	CFGW & 0x3BFF + SUM_ID	0x37CE	0x039C
PIC16F876	OFF	SUM[0x0000:0x1FFF] + CFGW & 0x3BFF	0x1BFF	0xE7CD
	0x1F00 : 0x1FFF	SUM[0x0000:0x1EFF] + CFGW & 0x3BFF +SUM_ID	0x28EE	0xDAA3
	0x1000 : 0x1FFF	SUM[0x0000:0x0FFF] + CFGW & 0x3BFF + SUM_ID	0x27DE	0xD993
	ALL	CFGW & 0x3BFF + SUM_ID	0x27CE	0xF39C
PIC16F877	OFF	SUM[0x0000:0x1FFF] + CFGW & 0x3BFF	0x1BFF	0xE7CD
	0x1F00 : 0x1FFF	SUM[0x0000:0x1EFF] + CFGW & 0x3BFF +SUM_ID	0x28EE	0xDAA3
	0x1000 : 0x1FFF	SUM[0x0000:0x0FFF] + CFGW & 0x3BFF + SUM_ID	0x27DE	0xD993
	ALL	CFGW & 0x3BFF + SUM_ID	0x27CE	0xF39C

Legend: CFGW = Configuration Word
SUM[a:b] = [Sum of locations a to b inclusive]
SUM_ID = ID locations masked by 0xF then made into a 16-bit value with ID0 as the most significant nibble.
For example, ID0 = 0x1, ID1 = 0x2, ID3 = 0x3, ID4 = 0x4, then SUM_ID = 0x1234
*Checksum = [Sum of all the individual expressions] **MODULO** [0xFFFF]
+ = Addition
& = Bitwise AND

5.0 PROGRAM/VERIFY MODE ELECTRICAL CHARACTERISTICS

5.1 Embedding Data EEPROM Contents in Hex File

The programmer should be able to read data EEPROM information from a hex file and conversely (as an option) write data EEPROM contents to a hex file along with program memory information and fuse information.

The 256 data memory locations are logically mapped starting at address 0x2100. The format for data memory storage is one data byte per address location, LSB aligned.

TABLE 5-1: AC/DC CHARACTERISTICS TIMING REQUIREMENTS FOR PROGRAM/VERIFY MODE

Standard Operating Conditions (unless otherwise stated) **Operating Temperature: 0°C ≤ TA ≤ +70°C** **Operating Voltage: 4.5V ≤ VDD ≤ 5.5V**						
Characteristics	**Sym**	**Min**	**Typ**	**Max**	**Units**	**Conditions/Comments**
General						
VDD level for word operations, program memory	VDD	2.0		5.5	V	
VDD level for word operations, data memory	VDD	2.0		5.5	V	
VDD level for bulk erase/write operations, program and data memory	VDD	4.5		5.5	V	
High voltage on $\overline{MCLR}$ for high-voltage programming entry	VIHH	VDD + 3.5		13.5	V	
Voltag on $\overline{MCLR}$ for low-voltage programming entry	VIH	4.5		5.5	V	
$\overline{MCLR}$ rise time (VSS to VHH) for test mode entry	tVHHR			1.0	µs	
(RB6, RB7) input high level	VIH1	0.8VDD			V	Schmitt Trigger input
(RB6, RB7) input low level	VIL1	0.2VDD			V	Schmitt Trigger input
RB<7:4> setup time before $\overline{MCLR}$↑ (test mode selection pattern setup time)	tset0	100			ns	
RB<7:4> hold time after $\overline{MCLR}$↑ (test mode selection pattern setup time)	thld0	5			µs	
Serial Program/Verify						
Data in setup time before clock↓	tset1	100			ns	
Data in hold time after clock↓	thld1	100			ns	
Data input not driven to next clock input (delay required between command/data or command/command)	tdly1	1.0			µs	
Delay between clock↓ to clock↑ of next command or data	tdly2	1.0			µs	
Clock↑ to data out valid (during read data)	tdly3	80			ns	
Erase cycle time	tera		2	5	ms	
Programming cycle time	tprog		2	5	ms	

FIGURE 5-1: LOAD DATA COMMAND HIGH-VOLTAGE MODE (PROGRAM/VERIFY)

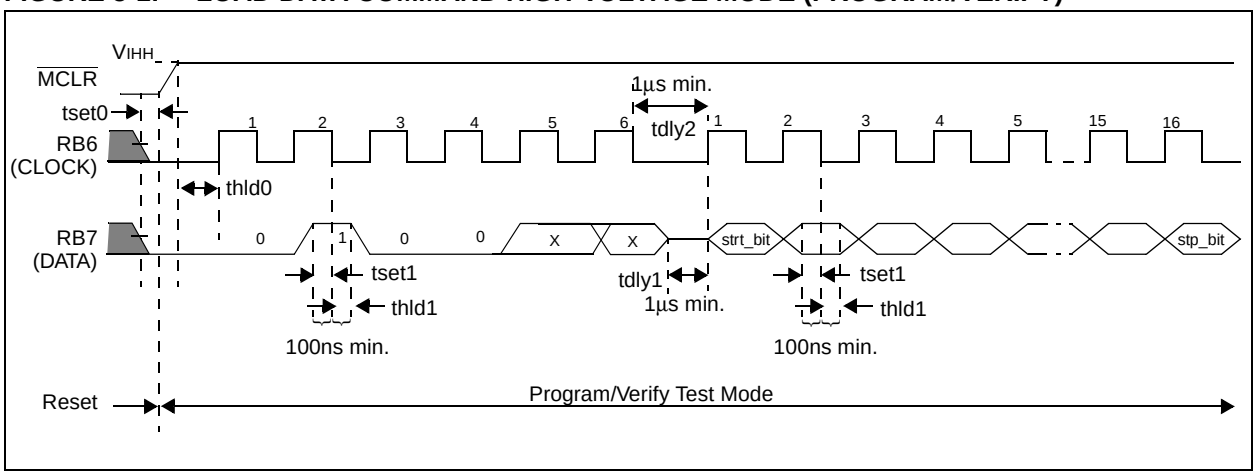


FIGURE 5-2: READ DATA COMMAND HIGH-VOLTAGE MODE (PROGRAM/VERIFY)

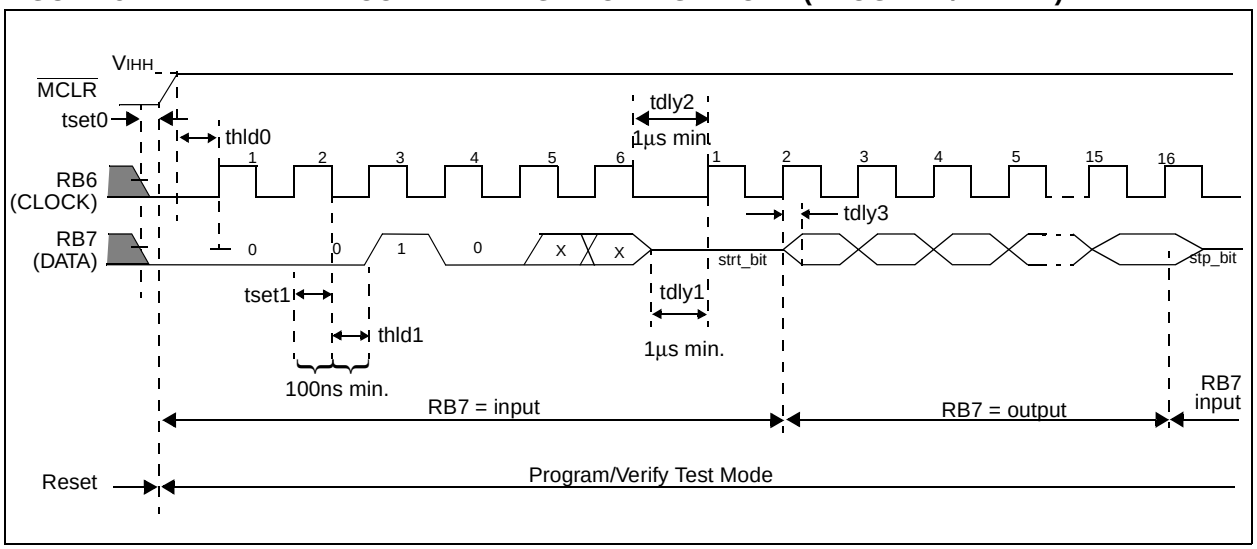


FIGURE 5-3: INCREMENT ADDRESS COMMAND HIGH-VOLTAGE MODE (PROGRAM/VERIFY)

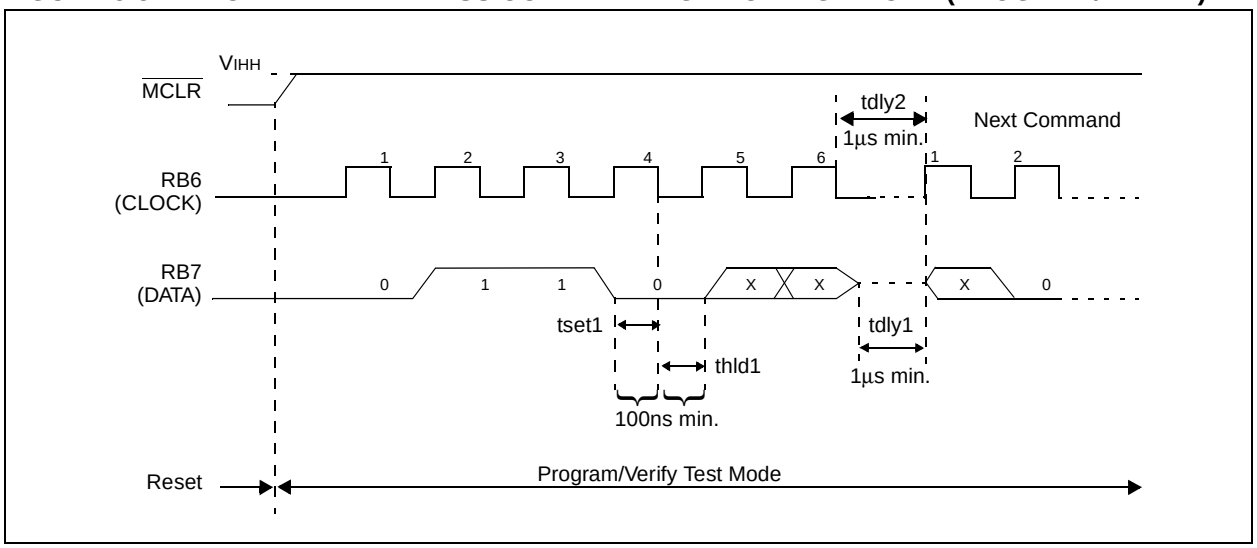


FIGURE 5-4: LOAD DATA COMMAND LOW-VOLTAGE MODE (PROGRAM/VERIFY)

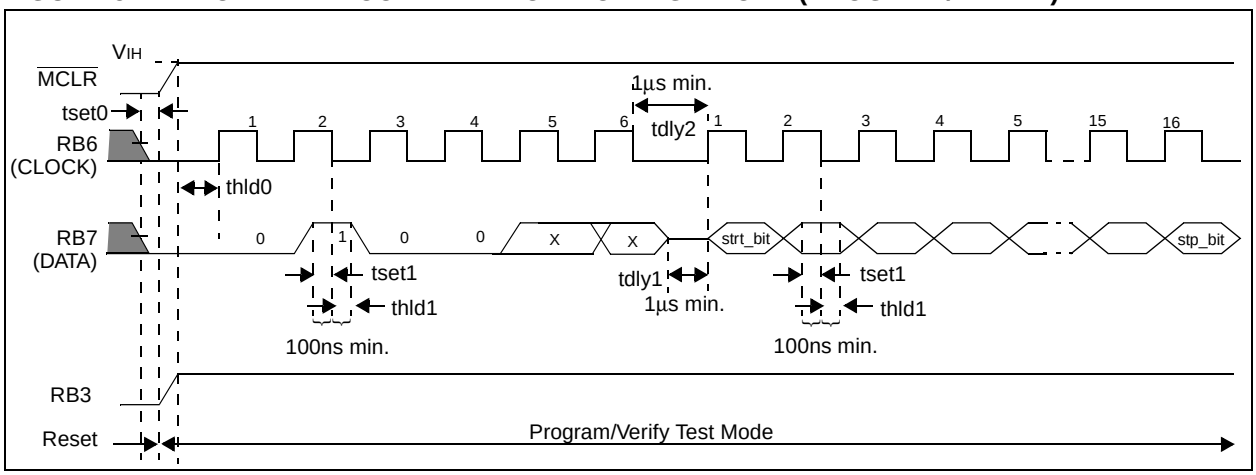


FIGURE 5-5: READ DATA COMMAND LOW-VOLTAGE MODE (PROGRAM/VERIFY)

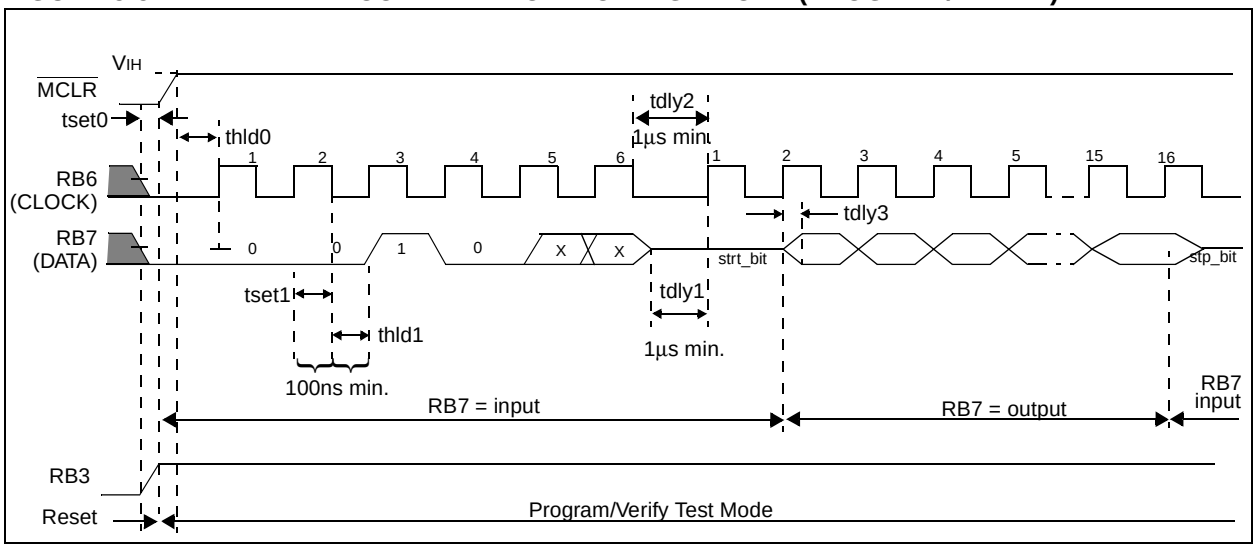
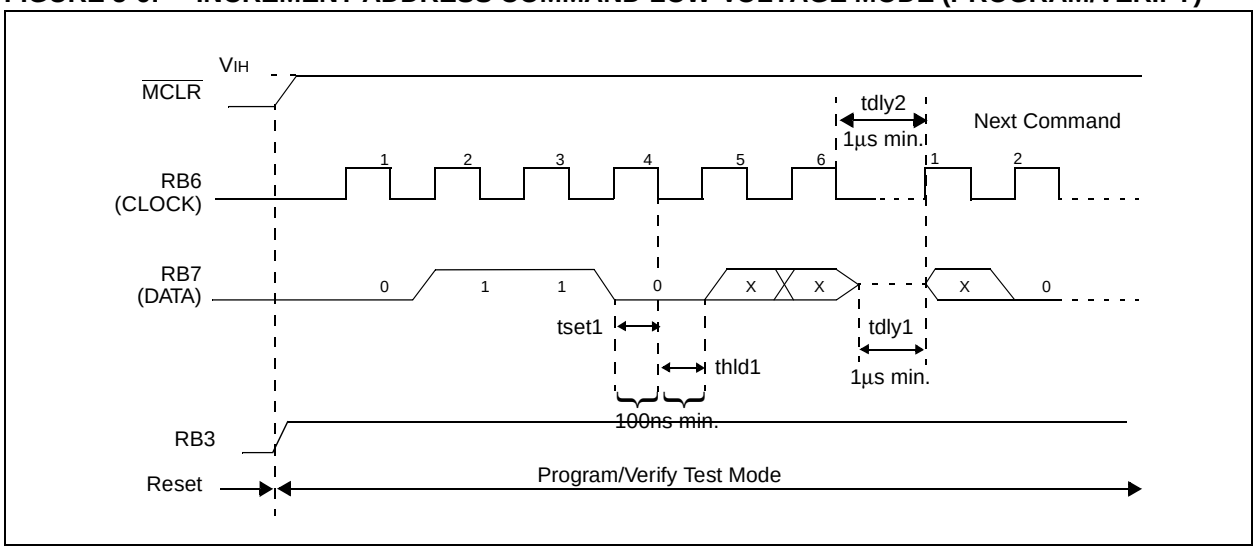


FIGURE 5-6: INCREMENT ADDRESS COMMAND LOW-VOLTAGE MODE (PROGRAM/VERIFY)



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